

# IRF7458TR Datasheet



DiGi Electronics Part Number	IRF7458TR-DG
Manufacturer	<a href="#">Infineon Technologies</a>
Manufacturer Product Number	IRF7458TR
Description	MOSFET N-CH 30V 14A 8SO
Detailed Description	N-Channel 30 V 14A (Ta) 2.5W (Ta) Surface Mount 8-SO

<https://www.DiGi-Electronics.com>



Tel: +00 852-30501935

RFQ Email: [Info@DiGi-Electronics.com](mailto:Info@DiGi-Electronics.com)

DiGi is a global authorized distributor of electronic components.

## Purchase and inquiry

Manufacturer Product Number:

IRF7458TR

Series:

HEXFET®

FET Type:

N-Channel

Drain to Source Voltage (Vdss):

30 V

Drive Voltage (Max Rds On, Min Rds On):

10V, 16V

Vgs(th) (Max) @ Id:

4V @ 250µA

Vgs (Max):

±30V

FET Feature:

-

Operating Temperature:

-55°C ~ 150°C (Tj)

Supplier Device Package:

8-SO

Manufacturer:

Infineon Technologies

Product Status:

Obsolete

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (Id) @ 25°C:

14A (Ta)

Rds On (Max) @ Id, Vgs:

8mOhm @ 14A, 16V

Gate Charge (Qg) (Max) @ Vgs:

59 nC @ 10 V

Input Capacitance (Ciss) (Max) @ Vds:

2410 pF @ 15 V

Power Dissipation (Max):

2.5W (Ta)

Mounting Type:

Surface Mount

Package / Case:

8-SOIC (0.154", 3.90mm Width)

## Environmental & Export classification

RoHS Status:

RoHS non-compliant

REACH Status:

REACH Unaffected

HTSUS:

8541.29.0095

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99



International  
**IR** Rectifier

**SMPS MOSFET**

PD- 93892C

**IRF7458**

### Applications

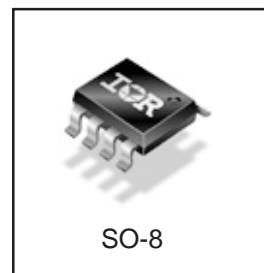
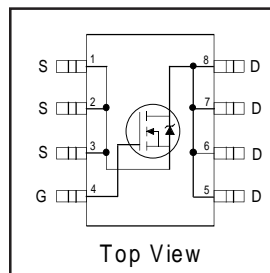
- High Frequency Isolated DC-DC Converters with Synchronous Rectification for Telecom and Industrial Use
- High Frequency Buck Converters for Computer Processor Power

HEXFET® Power MOSFET

$V_{DSS}$	$R_{DS(on) \max}$	$I_D$
<b>30V</b>	<b>8.0m<math>\Omega</math></b>	<b>14A</b>

### Benefits

- Ultra-Low Gate Impedance
- Very Low  $R_{DS(on)}$
- Fully Characterized Avalanche Voltage and Current



### Absolute Maximum Ratings

Symbol	Parameter	Max.	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 30$	V
$I_D @ T_A = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$	14	A
$I_D @ T_A = 70^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$	11	
$I_{DM}$	Pulsed Drain Current <sup>①</sup>	110	
$P_D @ T_A = 25^\circ\text{C}$	Maximum Power Dissipation <sup>③</sup>	2.5	W
$P_D @ T_A = 70^\circ\text{C}$	Maximum Power Dissipation <sup>③</sup>	1.6	W
	Linear Derating Factor	0.02	mW/ $^\circ\text{C}$
$T_J, T_{STG}$	Junction and Storage Temperature Range	-55 to + 150	$^\circ\text{C}$

### Thermal Resistance

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JL}$	Junction-to-Drain Lead	—	20	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-Ambient <sup>④</sup>	—	50	

Notes <sup>①</sup> through <sup>④</sup> are on page 8  
[www.irf.com](http://www.irf.com)

## IRF7458

International  
IR RectifierStatic @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	30	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.029	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}, I_D = 1mA$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	6.3	8.0	m $\Omega$	$V_{GS} = 16V, I_D = 14A$ ③
		—	7.0	9.0		$V_{GS} = 10V, I_D = 11A$ ③
$V_{GS(th)}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
$I_{DSS}$	Drain-to-Source Leakage Current	—	—	20	$\mu A$	$V_{DS} = 24V, V_{GS} = 0V$
		—	—	100		$V_{DS} = 24V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
$I_{GSS}$	Gate-to-Source Forward Leakage	—	—	200	nA	$V_{GS} = 24V$
	Gate-to-Source Reverse Leakage	—	—	-200		$V_{GS} = -24V$

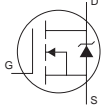
Dynamic @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$g_{fs}$	Forward Transconductance	26	—	—	S	$V_{DS} = 15V, I_D = 11A$
$Q_g$	Total Gate Charge	—	39	59	nC	$I_D = 11A$
$Q_{gs}$	Gate-to-Source Charge	—	11	17		$V_{DS} = 15V$
$Q_{gd}$	Gate-to-Drain ("Miller") Charge	—	8.7	13		$V_{GS} = 10V$ ③
$Q_{oss}$	Output Gate Charge	—	29	44		$V_{GS} = 0V, V_{DS} = 16V$
$t_{d(on)}$	Turn-On Delay Time	—	10	—	ns	$V_{DD} = 15V$
$t_r$	Rise Time	—	4.6	—		$I_D = 11A$
$t_{d(off)}$	Turn-Off Delay Time	—	22	—		$R_G = 1.8\Omega$
$t_f$	Fall Time	—	5.0	—		$V_{GS} = 10V$ ③
$C_{iss}$	Input Capacitance	—	2410	—	pF	$V_{GS} = 0V$
$C_{oss}$	Output Capacitance	—	1100	—		$V_{DS} = 15V$
$C_{rss}$	Reverse Transfer Capacitance	—	110	—		$f = 1.0MHz$

## Avalanche Characteristics

Symbol	Parameter	Typ.	Max.	Units
$E_{AS}$	Single Pulse Avalanche Energy②	—	280	mJ
$I_{AR}$	Avalanche Current①	—	11	A

## Diode Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	2.3	A	MOSFET symbol showing the integral reverse p-n junction diode. 
$I_{SM}$	Pulsed Source Current (Body Diode) ①	—	—	110		
$V_{SD}$	Diode Forward Voltage	—	0.82	1.3	V	$T_J = 25^\circ\text{C}, I_S = 11A, V_{GS} = 0V$ ③
		—	0.68	—		$T_J = 125^\circ\text{C}, I_S = 11A, V_{GS} = 0V$
$t_{rr}$	Reverse Recovery Time	—	51	77	ns	$T_J = 25^\circ\text{C}, I_F = 11A, V_R = 20V$
$Q_{rr}$	Reverse Recovery Charge	—	87	130	nC	$di/dt = 100A/\mu s$ ③
$t_{rr}$	Reverse Recovery Time	—	52	78	ns	$T_J = 125^\circ\text{C}, I_F = 11A, V_R = 20V$
$Q_{rr}$	Reverse Recovery Charge	—	93	140	nC	$di/dt = 100A/\mu s$ ③

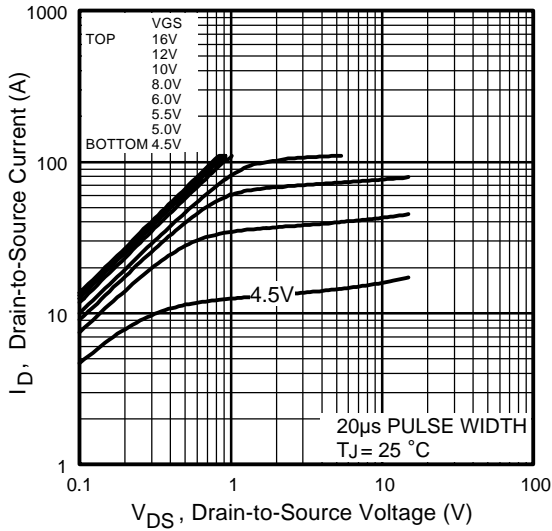


Fig 1. Typical Output Characteristics

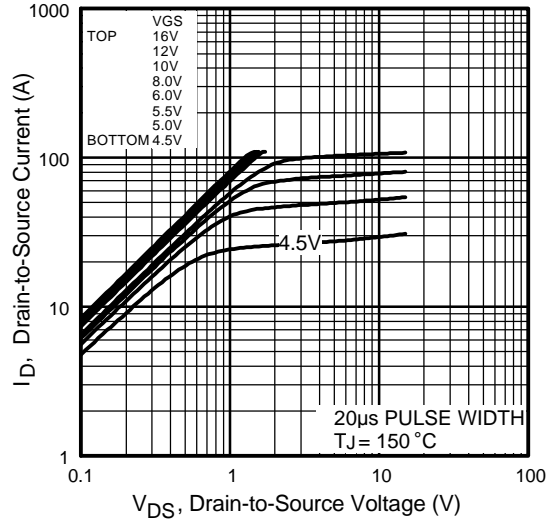


Fig 2. Typical Output Characteristics

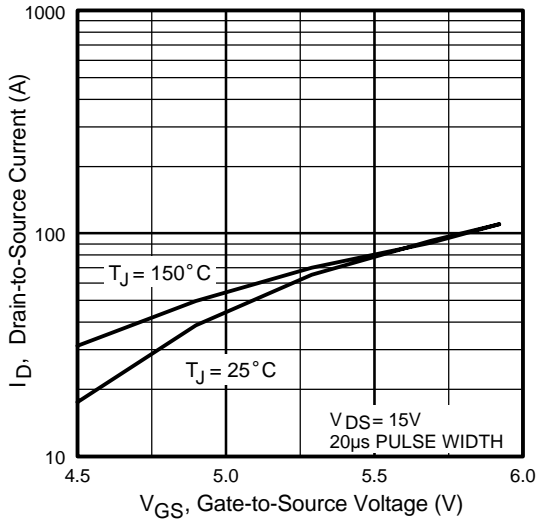


Fig 3. Typical Transfer Characteristics

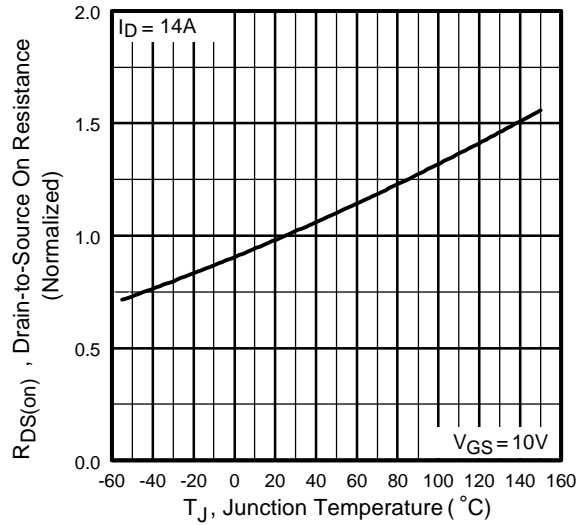
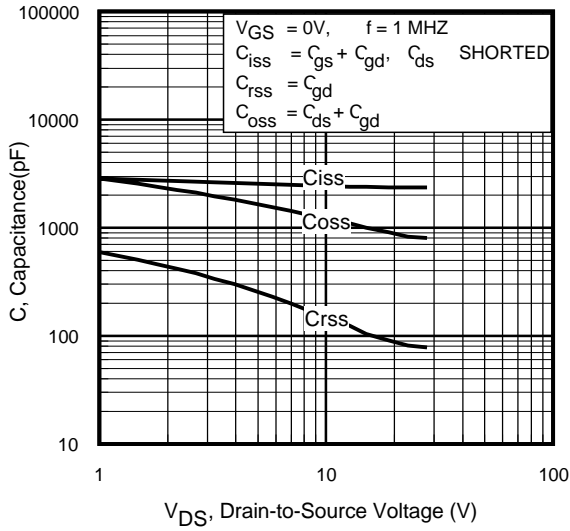


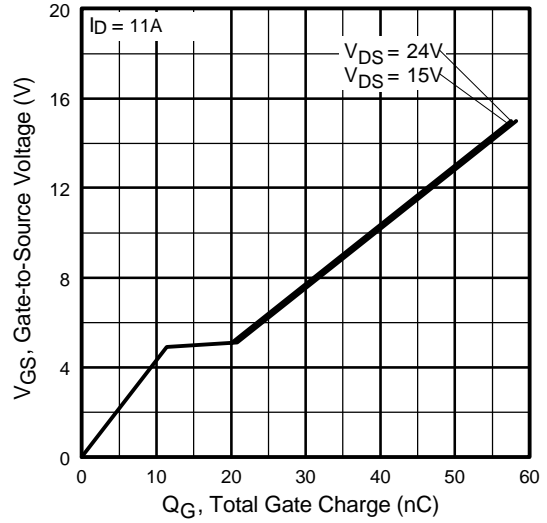
Fig 4. Normalized On-Resistance Vs. Temperature

# IRF7458

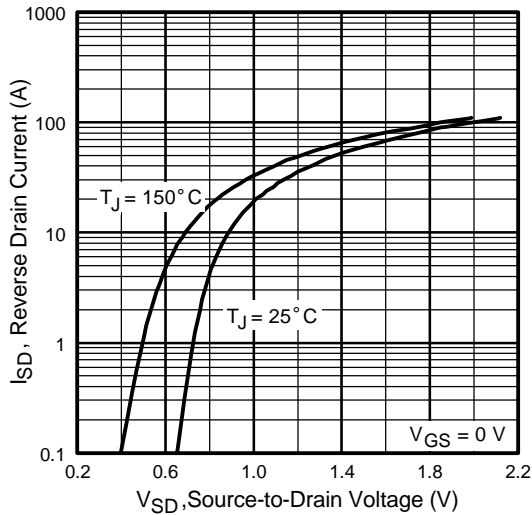
International  
**IR** Rectifier



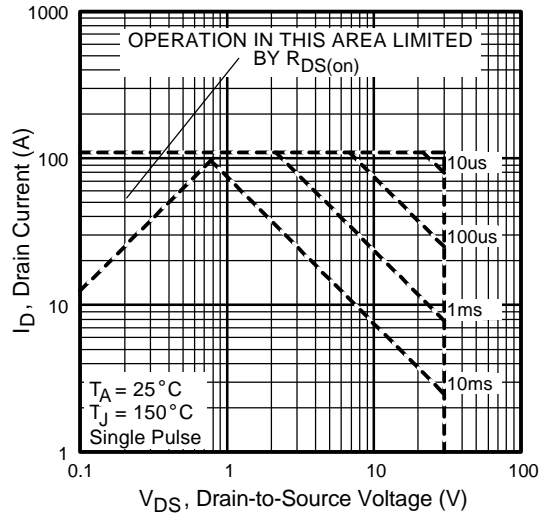
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



**Fig 7.** Typical Source-Drain Diode Forward Voltage



**Fig 8.** Maximum Safe Operating Area

Fig 6. On-Resistance Vs. Drain Current

International  
IR Rectifier

IRF7458

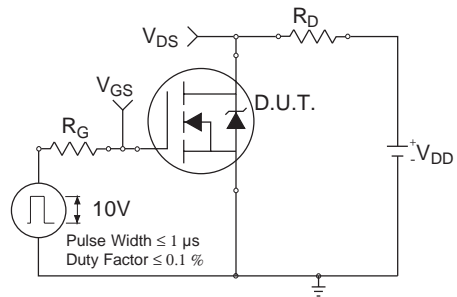
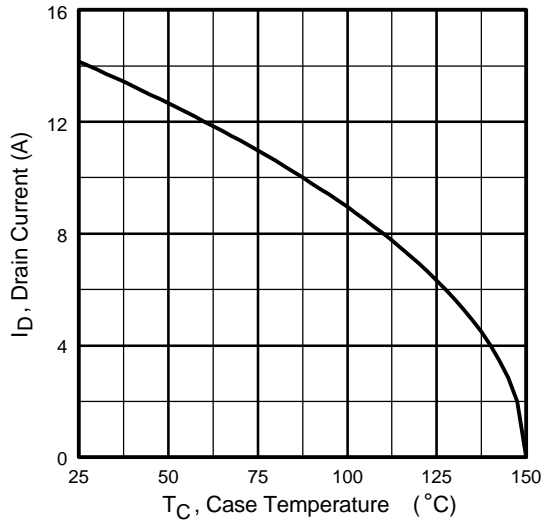


Fig 10a. Switching Time Test Circuit

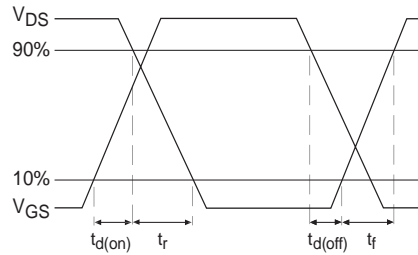


Fig 10b. Switching Time Waveforms

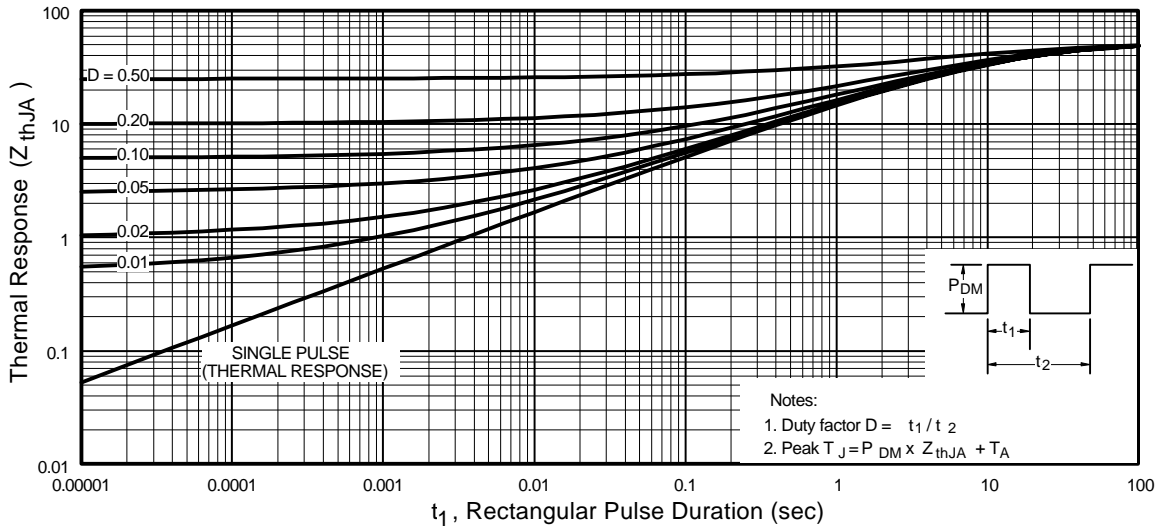
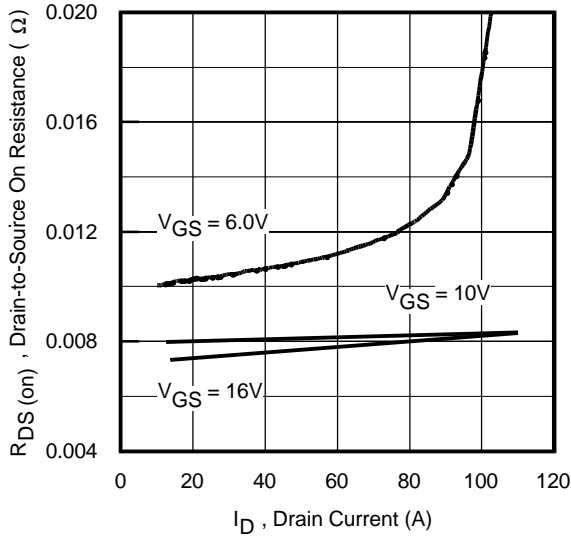


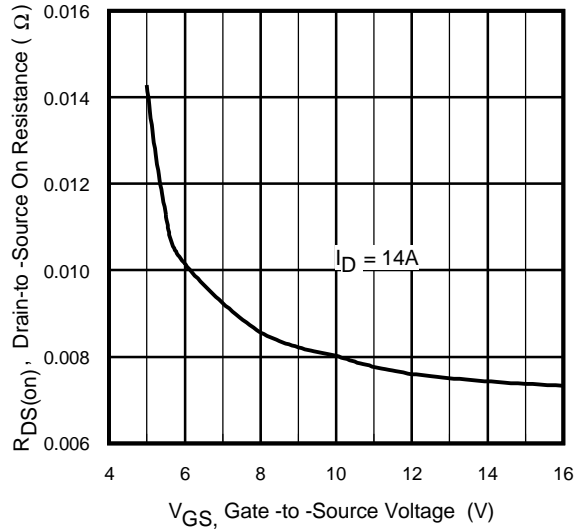
Fig 10. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

# IRF7458

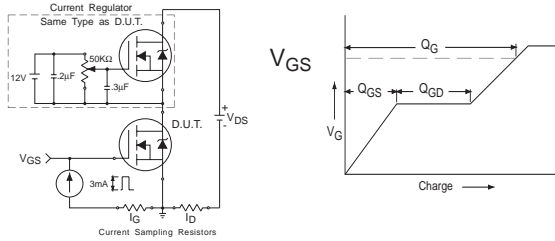
International  
**IR** Rectifier



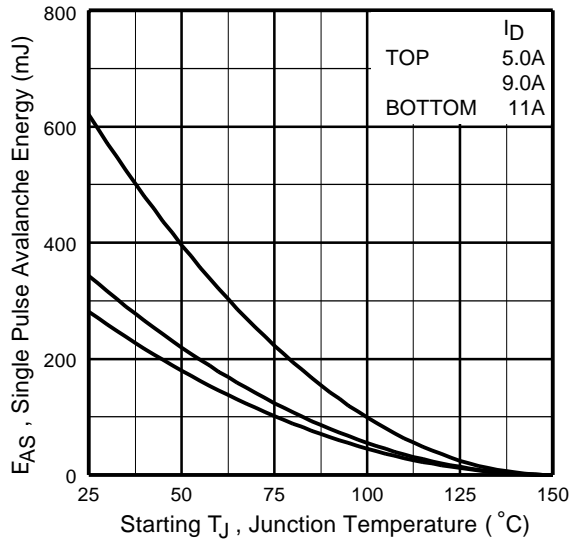
**Fig 12.** On-Resistance Vs. Drain Current



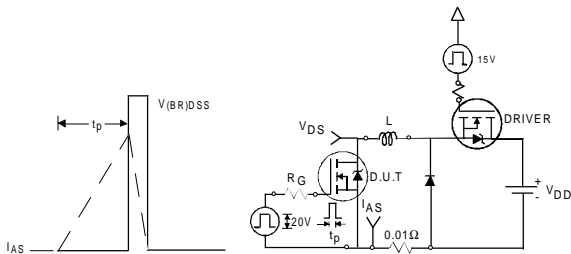
**Fig 13.** On-Resistance Vs. Gate Voltage



**Fig 13a&b.** Basic Gate Charge Test Circuit and Waveform



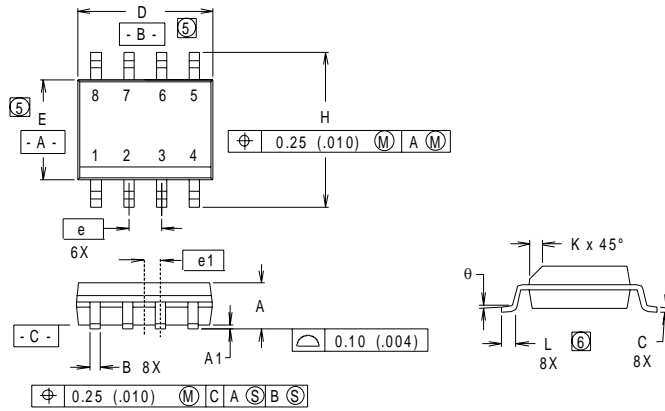
**Fig 14c.** Maximum Avalanche Energy Vs. Drain Current



**Fig 14a&b.** Unclamped Inductive Test circuit and Waveforms

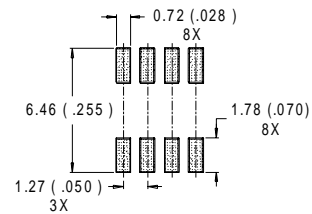


## SO-8 Package Details



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
B	.014	.018	0.36	0.46
C	.0075	.0098	0.19	0.25
D	.189	.196	4.80	4.98
E	.150	.157	3.81	3.99
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.011	.019	0.28	0.48
L	0.16	.050	0.41	1.27
$\theta$	0°	8°	0°	8°

**RECOMMENDED FOOTPRINT**

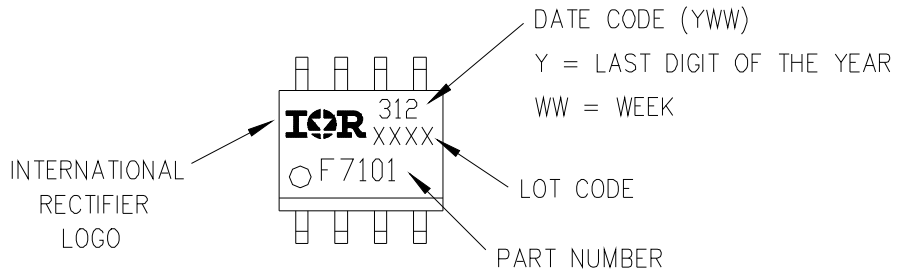


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION : INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS  
MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.006).
6. DIMENSIONS IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE..

## SO-8 Part Marking

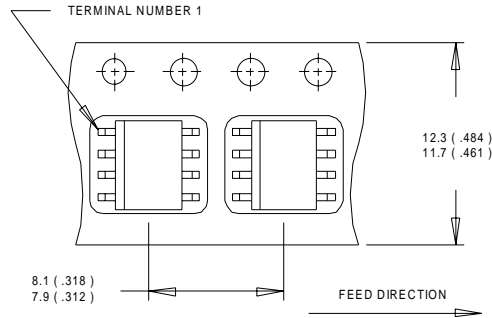
EXAMPLE: THIS IS AN IRF7101



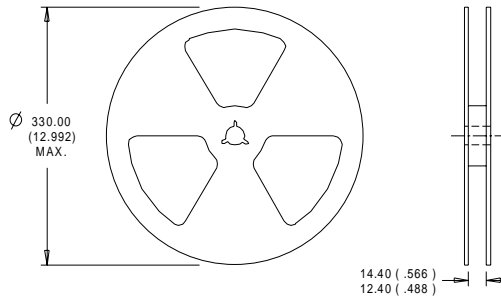
# IRF7458

International  
**IR** Rectifier

## SO-8 Tape and Reel



- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
  2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
  3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
  2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Starting  $T_J = 25^\circ\text{C}$ ,  $L = 4.6\text{mH}$   
 $R_G = 25\Omega$ ,  $I_{AS} = 11\text{A}$ .
- ③ Pulse width  $\leq 400\mu\text{s}$ ; duty cycle  $\leq 2\%$ .
- ④ When mounted on 1 inch square copper board,  $t < 10\text{ sec}$

Data and specifications subject to change without notice.  
This product has been designed and qualified for the Industrial market.  
Qualification Standards can be found on IR's Web site.

International  
**IR** Rectifier

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105  
TAC Fax: (310) 252-7903

Visit us at [www.irf.com](http://www.irf.com) for sales contact information. 3/01

[www.irf.com](http://www.irf.com)

## OUR CERTIFICATE

DiGi provide top-quality products and perfect service for customer worldwide through standardization, technological innovation and continuous improvement. DiGi through third-party certification, we stricly control the quality of products and services. Welcome your RFQ to

Email: [Info@DiGi-Electronics.com](mailto:Info@DiGi-Electronics.com)



Tel: +00 852-30501935

RFQ Email: [Info@DiGi-Electronics.com](mailto:Info@DiGi-Electronics.com)

DiGi is a global authorized distributor of electronic components.